



The ZM600N15HP combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

Trench technology  
 $DS(ON)$  to minimize conductive loss

**T<sub>c</sub> =25**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D@TC=25$	28	A
	$I_D@TC=75$	21	A
	$I_D@TC=100$	17	A
Pulsed Drain Current	$I_{DM}$	60	A
Total Power Dissipation( $TC=25^\circ C$ )	$P_D@TC=25$	80	W
Total Power Dissipation( $TA=25^\circ C$ )	$P_D@TA=25$	5	W
Operating Junction Temperature	$T_J$	-55 to 150	
Storage Temperature	$T_{STG}$	-55 to 150	

**Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	1.5	° C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	25	° C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	° C

**Electrical characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	150			V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.0		4.0	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V			1.0	uA
Gate- Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V ,V <sub>DS</sub> =0V			100	nA
Static Drain-source On Resistance		V <sub>GS</sub> =10V, I <sub>D</sub> =20A				
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =20A				
Source-drain voltage	V <sub>SD</sub>					





Fig.7 Switching Time Measurement Circuit

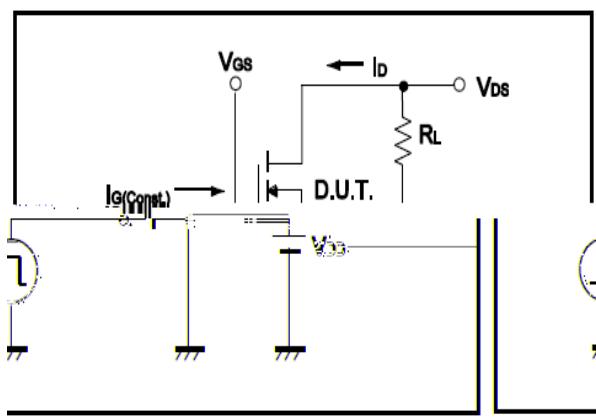


Fig.8 Gate Charge Waveform

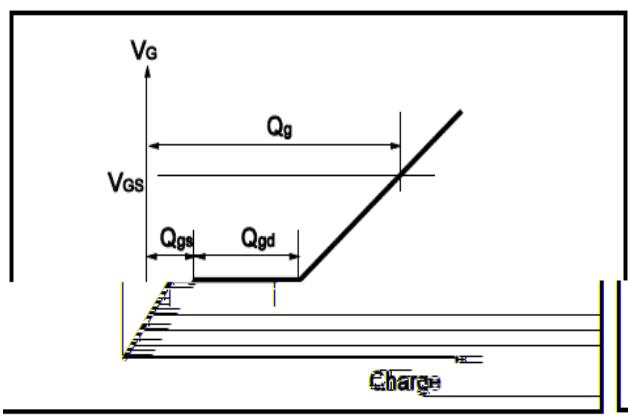


Fig.9 Switching Time Measurement Circuit

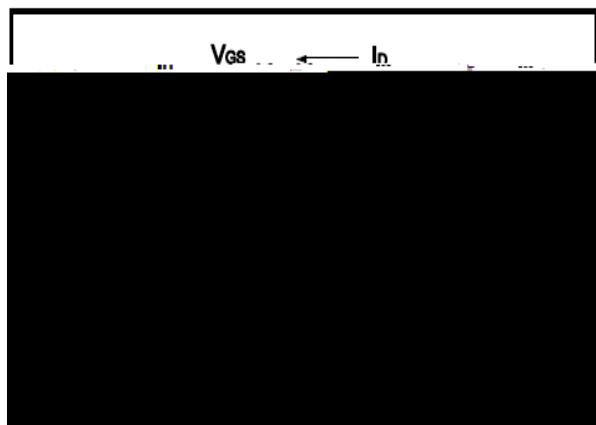


Fig.10 Gate Charge Waveform

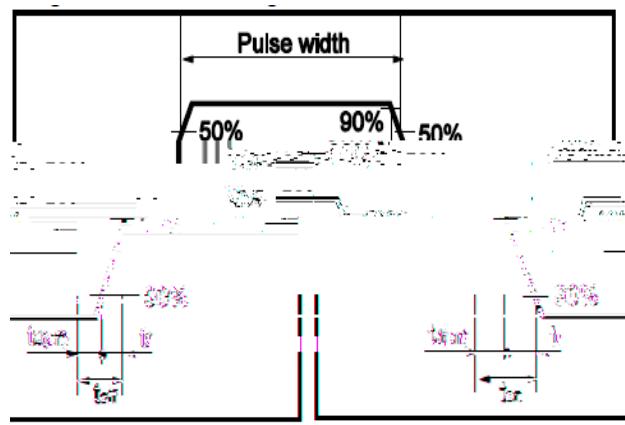


Fig.11 Avalanche Measurement Circuit

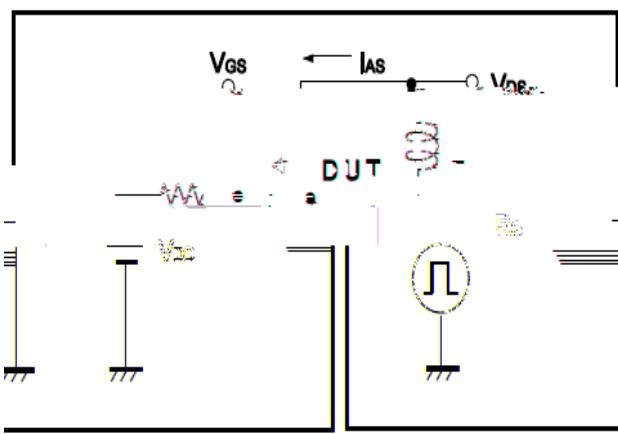


Fig.12 Avalanche Waveform

